

SOT1855-1

wafer level chip-scale package; 29 bumps; 1.14 x 1.14 x 0.28 mm

7 October 2016

Package information

1. Package summary

Dimensions (mm)	1.14 x 1.14 x 0.28
Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package outline version code	SOT1855-1
Manufacturer package code	SOT1855
Package type industry code	WLCSP29
Package outline version description	wafer level chip-scale package; 29 bumps; 1.14 x 1.14 x 0.28 mm
Package style descriptive code	WLCSP
Package body material type	X
Mounting method type	S (surface mount)
Package life cycle status	REL
Security status	COMPANY PUBLIC
Issue date	4-10-2016
Customer specific indicator	N
Maturity	Product

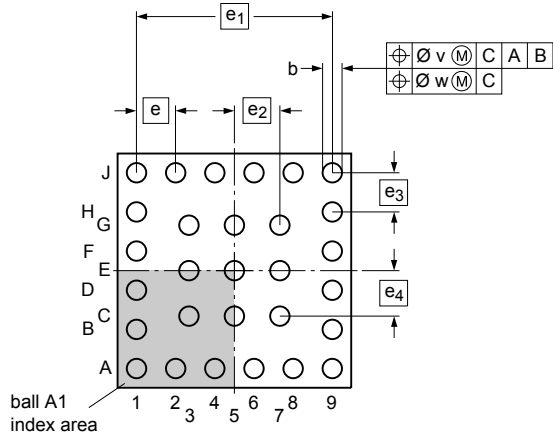
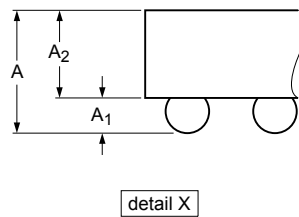
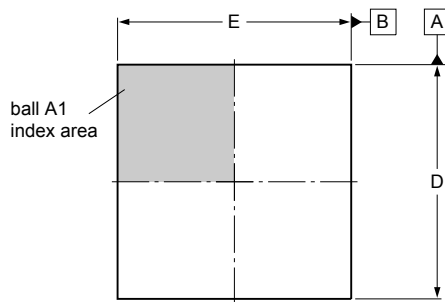
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A ₂	package height	0.18	-	0.2	0.22	mm
A	seated height	0.255	-	0.28	0.305	mm
D	package length	1.11	-	1.14	1.17	mm
E	package width	1.11	-	1.14	1.17	mm
e	nominal pitch	-	-	0.19	-	mm
n ₂	actual quantity of termination	-	-	29	-	



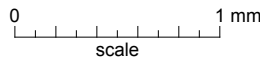
2. Package outline

WLSCP29: wafer level chip-scale package; 29 bumps; 1.14 x 1.14 x 0.28 mm SOT1855-1



Bumps Coordination
* (0,0) at package center

Bump	X (µm)	Y (µm)
A1	-475.0	-475.0
B1	-475.0	-285.0
D1	-475.0	-95.0
F1	-475.0	95.0
H1	-475.0	285.0
J1	-475.0	475.0
A2	-285.0	-475.0
J2	-285.0	475.0
C3	-220.0	-220.0
E3	-220.0	0.0
G3	-220.0	220.0
A4	-95.0	-475.0
J4	-95.0	475.0
C5	0.0	-220.0
E5	0.0	0.0
G5	0.0	220.0
A6	95.0	-475.0
J6	95.0	475.0
C7	220.0	-220.0
E7	220.0	0.0
G7	220.0	220.0
A8	285.0	-475.0
J8	285.0	475.0
A9	475.0	-475.0
B9	475.0	-285.0
D9	475.0	-95.0
F9	475.0	95.0
H9	475.0	285.0
J9	475.0	475.0



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	e ₃	e ₄	v	w	y
max	0.305	0.095	0.22	0.115	1.17	1.17								
nom	0.280	0.080	0.20	0.100	1.14	1.14	0.19	0.95	0.22	0.19	0.22	0.05	0.015	0.03
min	0.255	0.065	0.18	0.085	1.11	1.11								

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1855-1	---	---	---		-16-02-24- 16-10-04

Fig. 1. Package outline WLCSP29 (SOT1855-1)

3. Legal information

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